LNJ115W8HRA

Surface Mounting Chip LED

TSS Bi-Color Type

■ Absolute Maximum Ratings $T_a = 25$ °C

• Blue

Parameter	Symbol	Rating	Unit	
Power dissipation	P_{D}	40	mW	
Forward current	I_{F}	10	mA	
Pulse forward current *	I_{FP}	50	mA	
Reverse voltage	V _R	5	V	
Operating ambient temperature	T _{opr}	-30 to +85	°C	
Storage temperature	T _{stg}	-40 to +100	°C	

Note) *: The condition of I_{FP} is duty 10%, Pulse width 1 msec.

• Red

Parameter	Symbol	Rating	Unit	
Power dissipation	P_{D}	55	mW	
Forward current	I_{F}	20	mA	
Pulse forward current *	I _{FP}	60	mA	
Reverse voltage	V _R	3	V	
Operating ambient temperature	T _{opr}	-30 to +80	°C	
Storage temperature	T _{stg}	-40 to +100	°C °C	

Note) *: The condition of I_{FP} is duty 10%, Pulse width 1 msec.

■ Electro-Optical Characteristics $T_a = 25$ °C

• Blue

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Luminous intensity	I _O		4.0	8.4		mcd
Forward current	I_{F}			5		mA
Forward voltage	$V_{\rm F}$	$I_F = 5 \text{ mA}$		3.2	3.7	V
Peak emission wavelength	$\lambda_{ m P}$	$I_F = 5 \text{ mA}$		470		nm
Spectral half band width	Δλ	$I_F = 5 \text{ mA}$		30		nm
Reverse current	I_R	$V_R = 5 V$			10	μΑ

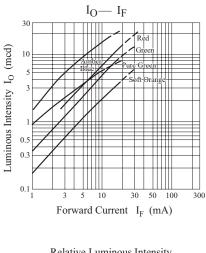
■ Lighting Color / Lens Color

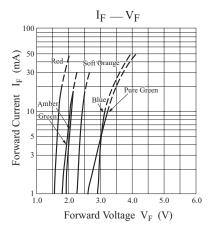
- Blue / White Diffused
- Red / White Diffused

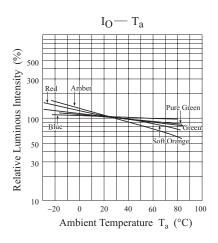
■ Electro-Optical Characteristics (Continued) $T_a = 25$ °C

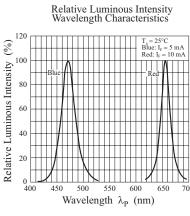
• Red

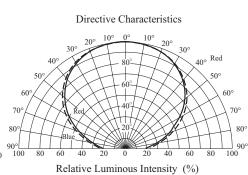
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Luminous intensity	I _O		2.8	6.7		mcd
Forward current	I_{F}			10		mA
Forward voltage	V_{F}	$I_F = 10 \text{ mA}$		1.72	2.6	V
Peak emission wavelength	λ_{P}	$I_F = 10 \text{ mA}$		655		nm
Spectral half band width	Δλ	$I_F = 10 \text{ mA}$		20		nm
Reverse current	I_R	$V_R = 3 V$			100	μΑ

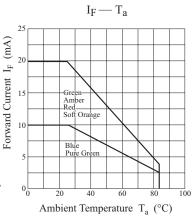












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